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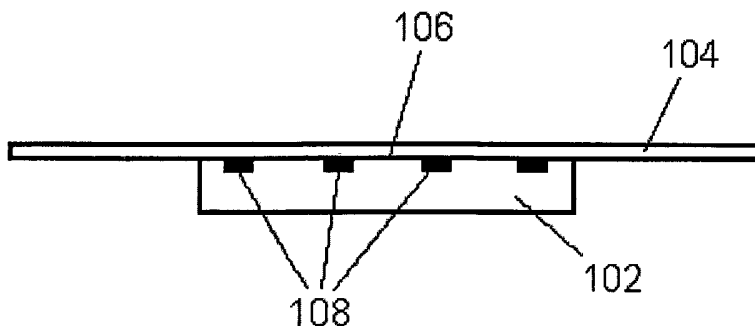
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(54) Title: DIRECT BUILD-UP LAYER ON AN ENCAPSULATED DIE PACKAGE



(57) Abstract: A microelectronic package including a microelectronic die having an active surface and at least one side. An encapsulation material is disposed adjacent the microelectronic die side(s), wherein the encapsulation material includes at least one surface substantially planar to the microelectronic die active surface. A first dielectric material layer may be disposed on at least a portion of the microelectronic die active surface and the encapsulation material surface. At least one conductive trace is then disposed on the first dielectric material layer. The conductive trace(s) is in electrical contact with the microelectronic die active surface. At least one conductive trace extends adjacent the microelectronic die active surface and adjacent the encapsulation material surface.



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INTERNATIONAL SEARCH REPORT

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According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)
IPC 7 H01L

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practical, search terms used)

EPO-Internal, WPI Data, PAJ

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X A	EP 0 611 129 A (GEN ELECTRIC) 17 August 1994 (1994-08-17) abstract; figures 1A, 1E, 4A, 5B, 8D column 1, line 55 -column 2, line 51 column 5, line 37 -column 7, line 3 column 9, line 40 -column 12, line 46 column 15, line 19 - line 46 claims 1, 11-14, 17 ---	1-19 20-23
X A	US 5 291 066 A (NEUGEBAUER CONSTANTINE A ET AL) 1 March 1994 (1994-03-01) abstract; figure 1A column 1, line 45 -column 2, line 26 column 2, line 66 -column 3, line 68 --- -/--	1-3 5-8

Further documents are listed in the continuation of box C.

Patent family members are listed in annex.

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Information on patent family members

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